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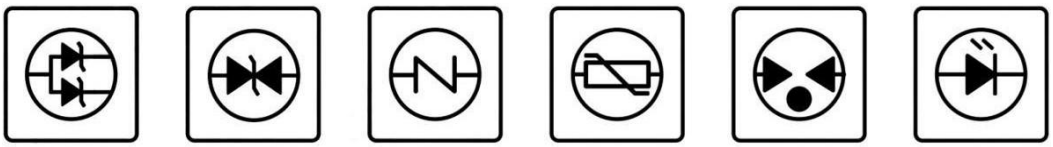
SEMICONDUCTOR




# NX7002BKR-MS

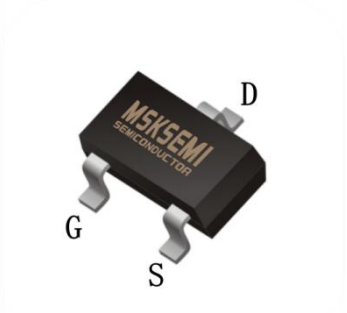
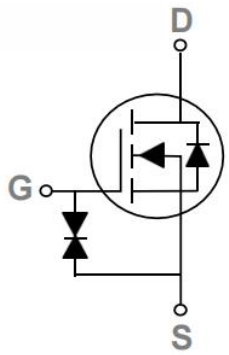
## Product specification

## Features

- 60V,0.3A, RDS(ON) =2.2Ω@VGS=10V
- Improved dv/dt capability
- Fast switching
- Green Device Available
- G-S ESD Protection Diode Embedded
- ESD protected up to 2KV

| BVDSS | RDSON | ID |
|---|---|---|
| 60V | 2.2Ω | 0.3A |

## Reference News

| PACKAGE OUTLINE | Pin Configuration | Marking |
|---|---|---|
|  SOT-23 |  |  |

## Absolute Maximum Ratings (TA=25℃ unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|---|---|---|---|
| $V_{DS}$ | Drain- Source Voltage | 60 | V |
| $V_{GS}$ | Gate- Source Voltage | ±20 | V |
| $I_D$ | Drain Current – Continuous ($T_C$=25℃) | 0.3 | A |
| | Drain Current – Continuous ($T_C$=100℃) | 0.1 | A |
| $I_{DM}$ | Drain Current – Pulsed[1] | 0.8 | A |
| $P_D$ | Power Dissipation ($T_C$=25℃) | 0.35 | W |
| | Power Dissipation – Derate above 25℃ | 0.003 | W/℃ |
| $T_{STG}$ | Storage Temperature Range | -50 to 150 | ℃ |
| $T_J$ | Operating Junction Temperature Range | -50 to 150 | ℃ |

## Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|---|---|---|---|---|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | --- | 357 | ℃/W |

## Electrical Characteristics(TJ=25 ℃ , unless otherwise noted)

### Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $BV_{DSS}$ | Drain- Source Breakdown Voltage | $V_{GS}$=0V , $I_D$=250uA | 60 | --- | --- | V |
| $I_{DSS}$ | Drain- Source Leakage Current | $V_{DS}$=60V , $V_{GS}$=0V , $T_J$=25℃ | --- | --- | 1 | uA |
| | | $V_{DS}$=48V , $V_{GS}$=0V , $T_J$=125℃ | --- | --- | 10 | uA |
| $I_{GSS}$ | Gate- Source Leakage Current | $V_{GS}$=±20V , $V_{DS}$=0V | --- | --- | ±10 | uA |

### On Characteristics

| | | | | | | |
|---|---|---|---|---|---|---|
| $R_{DS(ON)}$ | Static Drain- Source On- Resistance | $V_{GS}$=10V , $I_D$=0.3A | --- | 2.2 | 2.8 | Ω |
| | | $V_{GS}$=4.5V , $I_D$=0.2A | --- | 2 4 | 3 0 | Ω |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}$=$V_{DS}$ , $I_D$ =250uA | 1 | 1.6 | 2.5 | V |
| gfs | Forward Transconductance | $V_{DS}$=10V , $I_D$=0.3A | --- | 0.5 | --- | S |

### Dynamic and switching Characteristics

| | | | | | | |
|---|---|---|---|---|---|---|
| $Q_g$ | Total Gate Charge[2,3] | $V_{DS}$=30V , $V_{GS}$=10V , $I_D$=1A | --- | 3.7 | 5.6 | nC |
| $Q_{gs}$ | Gate-Source Charge[2,3] | | --- | 0.9 | 1.4 | |
| $Q_{gd}$ | Gate-Drain Charge[2,3] | | --- | 0.4 | 0.6 | |
| $T_{d(on)}$ | Turn-On Delay Time[2,3] | $V_{DD}$=30V ,$V_{GS}$=10V , $R_G$=6 Ω $I_D$=0.2A | --- | 3 | 6 | ns |
| $T_r$ | Rise Time[2,3] | | --- | 5 | 10 | |
| $T_{d(off)}$ | Turn-Off Delay Time[2,3] | | --- | 14 | 27 | |
| $T_f$ | Fall Time[2,3] | | --- | 9 | 17 | |
| $C_{iss}$ | Input Capacitance | $V_{DS}$=30V , $V_{GS}$=0V , F=1MHz | --- | 25.5 | 38 | pF |
| $C_{oss}$ | Output Capacitance | | --- | 17 | 26 | |
| $C_{rss}$ | Reverse Transfer Capacitance | | --- | 7.8 | 12 | |

### Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| $I_S$ | Continuous Source Current | $V_G$=$V_D$=0V , Force Current | --- | --- | 0.3 | A |
| $I_{SM}$ | Pulsed Source Current | | --- | --- | 1.2 | A |
| $V_{SD}$ | Diode Forward Voltage | $V_{GS}$=0V , $I_S$=1A , $T_J$=25℃ | --- | --- | 1.2 | V |
| $t_{rr}$ | Reverse Recovery Time | $V_{GS}$=50V, $I_S$=1A , dI/dt=100A/μs $T_J$=25℃ | --- | 3.4 | --- | ns |
| $Q_{rr}$ | Reverse Recovery Charge | | --- | 0.7 | --- | nC |

**Note :**

1.Repetitive Rating : Pulsed width limited by maximum junction temperature.

2 . The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.

3 . Essentially independent of operating temperature.

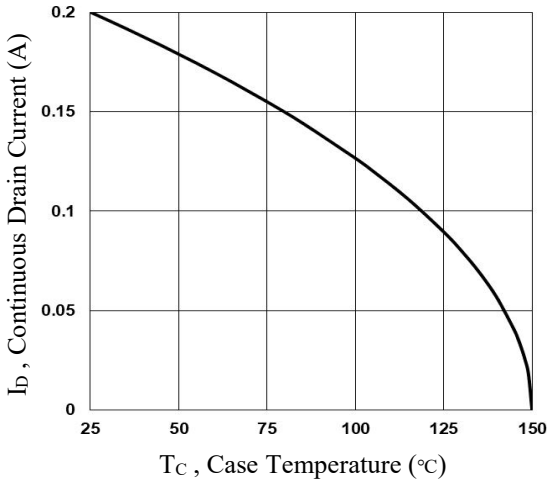



**Fig.1 Continuous Drain Current vs. $T_C$**

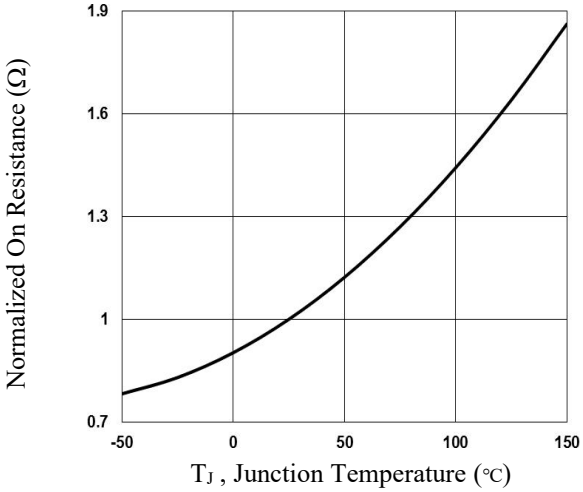



**Fig.2 Normalized RDSON vs. $T_J$**

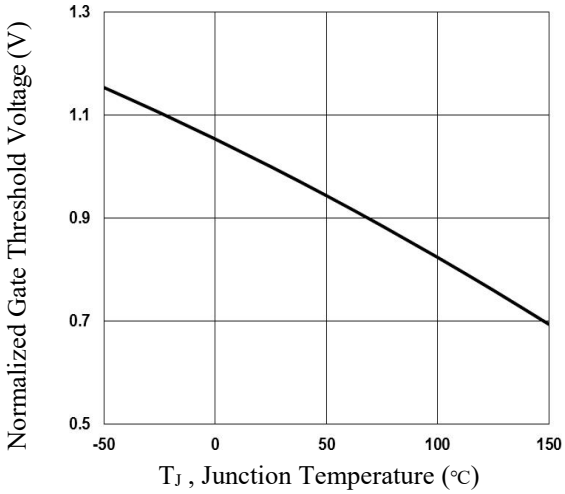



**Fig.3 Normalized $V_{th}$ vs. $T_J$**

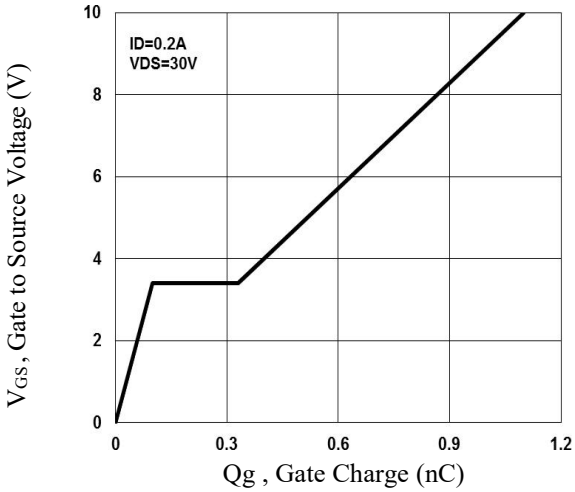



**Fig.4 Gate Charge Waveform**

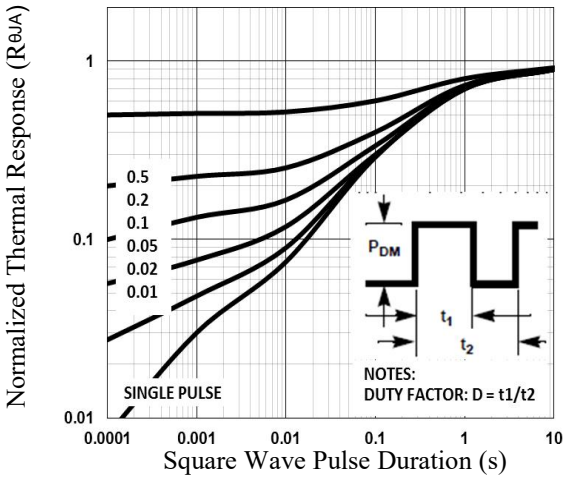



**Fig.5 Normalized Transient Impedance**

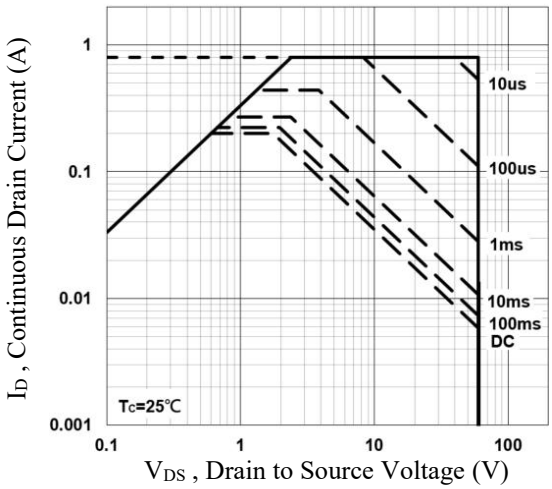
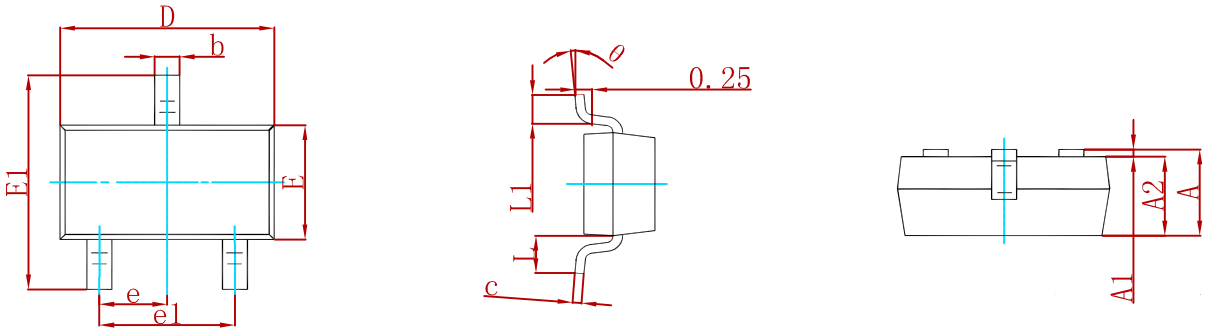


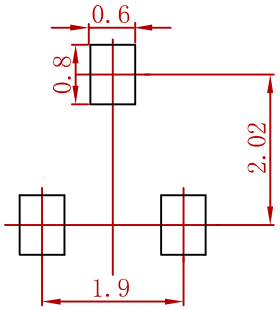

**Fig.6 Maximum Safe Operation Area**

## PACKAGE MECHANICAL DATA




| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|---|---|---|---|---|
| | Min | Max | Min | Max |
| A | 0.900 | 1.150 | 0.035 | 0.045 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 0.900 | 1.050 | 0.035 | 0.041 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.080 | 0.150 | 0.003 | 0.006 |
| D | 2.800 | 3.000 | 0.110 | 0.118 |
| E | 1.200 | 1.400 | 0.047 | 0.055 |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 |
| e | 0.950 TYP | | 0.037 TYP | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 |
| L | 0.550 REF | | 0.022 REF | |
| L1 | 0.300 | 0.500 | 0.012 | 0.020 |
| θ | 0° | 8° | 0° | 8° |

## Suggested Pad Layout




Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

## REEL SPECIFICATION

| P/N | PKG | QTY |
|---|---|---|
| NX7002BKR-MS | SOT-23 | 3000 |

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